

Title (en)
MULTI-CHEMISTRY PLATING SYSTEM

Title (de)
METALLABSCHIEDUNGSSYSTEM MIT MEHREREN CHEMISMEN

Title (fr)
SYSTEME DE GALVANISATION A CHIMIE MULTIPLE

Publication
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Application
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Abstract (en)
[origin: WO2004094702A2] Embodiments of the invention generally provide an electrochemical plating system. The plating system includes a substrate loading station positioned in communication with a mainframe processing platform, at least one substrate plating cell positioned on the mainframe, at least one substrate bevel cleaning cell positioned on the mainframe, and a stacked substrate annealing station positioned in communication with at least one of the mainframe and the loading station, each chamber in the stacked substrate annealing station having a heating plate, a cooling plate, and a substrate transfer robot therein.

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